



Title of Change:	Transfer of Assembly and Test operations for DPAK to ON Semiconductor Bien Hoa, Dong Nai Province, Vietnam.	
Proposed First Ship Date:	15 June 2018 <i>or earlier upon customer approval.</i>	
Product Category:	Active components – Integrated circuits	
Contact information	Contact your local ON Semiconductor Sales Office or < Richard.White@onsemi.com >	
Samples	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.	
Sample Availability Date:	May 30, 2017	
PPAP Availability Date:	May 30, 2017	
Additional Reliability Data	Contact your local ON Semiconductor Sales Office or < Peter.Turlo@onsemi.com >.	
Type of Notification	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >.	
Change Category:	Type of Change	
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	
Process – Assembly	Change of mold compound Change of product marking Move of all or part of assembly to a different location/site/subcontractor.	
Equipment - Assembly	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	
Description and Purpose:		
<p>This Final Notification announces the transfer of ON Semiconductor's assembly and test operations for the below listed DPAK package products, currently built at ON Semiconductor Seremban (TB), Malaysia to ON Semiconductor Bien Hoa, Dong Nai Province, Vietnam (VF).</p> <p>The changes to the assembly are:</p> <ol style="list-style-type: none"> The Mold Compound has been improved in the OSV bill of material. Changing from G700HC to G700HF. The G700HF has lower stress index than G700HC which helps lower package stress and lower tendency for delamination. 		
	Before Change Description	After Change Description
Mold Compound	MC EME-G700HC	G700HF
No Changes to the Final Test process or equipment.		
Reason / Motivation for Change:	Change Benefit: Rapid utilization of available capacity. Risk for late release: Limited Capacity	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	No anticipated impacts.	



Sites Affected:

All site(s)
 not applicable
 ON Semiconductor site(s) :
 External Foundry/Subcon site(s)

 ON Binh Duong Province, Vietnam

 ON Seremban, Malaysia

Marking of Parts/ Traceability of Change:

New Orderable Part Numbers are created.

Reliability Data Summary:

QV DEVICE NAME: NCV8401BDTRKG
PACKAGE ___ DPAK ___

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=150°C, 100 % max rated Vcc	1000 hrs	0/240
TC	JESD22-A104	Ta= -50°C to +150°C	1000 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/all
RSH	JESD22- B106	Ta = 265C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 10 sec		0/ 10

NOTE: AEC-1pager is attached.

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Current Part Number	New Part Number	Qualification Vehicle
NCV8401ADTRKG	NCV8401BDTRKG	NCV8401BDTRKG
NCV8403ADTRKG	NCV8403BDTRKG	
NCV8408DTRKG	NCV8408BDTRKG	
NCV8406ADTRKG	NCV8406BDTRKG	